

## P-Channel 20 V (D-S) MOSFET

| PRODU               | PRODUCT SUMMARY                    |       |                       |  |  |  |
|---------------------|------------------------------------|-------|-----------------------|--|--|--|
| V <sub>DS</sub> (V) | $R_{DS}(V)$ $R_{DS(on)}(\Omega)$   |       | Q <sub>g</sub> (Typ.) |  |  |  |
| - 20                | 0.080 at V <sub>GS</sub> = - 4.5 V | - 3.1 | 4.3 nC                |  |  |  |
| - 20                | 0.100 at V <sub>GS</sub> = - 2.5 V | - 2.3 | 4.5110                |  |  |  |

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

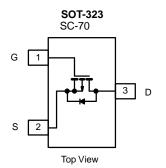
#### **APPLICATIONS**

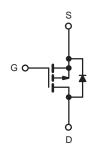
- Load Switch
- DC/DC Converters

 $T_J, T_{stq}$ 

- 50 to 150

260





P-Channel MOSFET

**ABSOLUTE MAXIMUM RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted) Symbol **Parameter** Limit Unit  $V_{DS}$ - 20 Drain-Source Voltage Gate-Source Voltage  $V_{GS}$ ± 12  $T_C = 25 \, ^{\circ}C$ - 3.1  $T_C = 70 \, ^{\circ}C$ - 2.1 Continuous Drain Current (T<sub>J</sub> = 150 °C)  $I_D$ - 1.4<sup>a, b</sup> T<sub>A</sub> = 25 °C T<sub>A</sub> = 70 °C - 1.1<sup>a, b</sup> Α Pulsed Drain Current - 6  $I_{DM}$  $T_C = 25 \, ^{\circ}C$ - 0.4 Continuous Source-Drain Diode Current  $I_S$ T<sub>A</sub> = 25 °C - 0.3 T<sub>C</sub> = 25 °C 0.5 T<sub>C</sub> = 70 °C 0.3  $P_D$ Maximum Power Dissipation W 0.4<sup>a, b</sup> T<sub>A</sub> = 25 °C T<sub>A</sub> = 70 °C 0.3<sup>a, b</sup>

#### Notes:

a. Surface mounted on 1" x 1" FR4 board.

Operating Junction and Storage Temperature Range

Soldering Recommendations (Peak Temperature)

b. t = 10 s.

c. Based on  $T_C$  = 25 °C.

°C



| THERMAL RESISTANCE RATINGS                  |              |                   |         |         |      |
|---|--------------|-------------------|---------|---------|------|
| Parameter                                   |              | Symbol            | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient <sup>a, b</sup> | t ≤ 10 s     | R <sub>thJA</sub> | 250     | 300     | °C/W |
| Maximum Junction-to-Foot (Drain)            | Steady State | R <sub>thJF</sub> | 225     | 270     | C/VV |

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Maximum under steady state conditions is 360 °C/W.

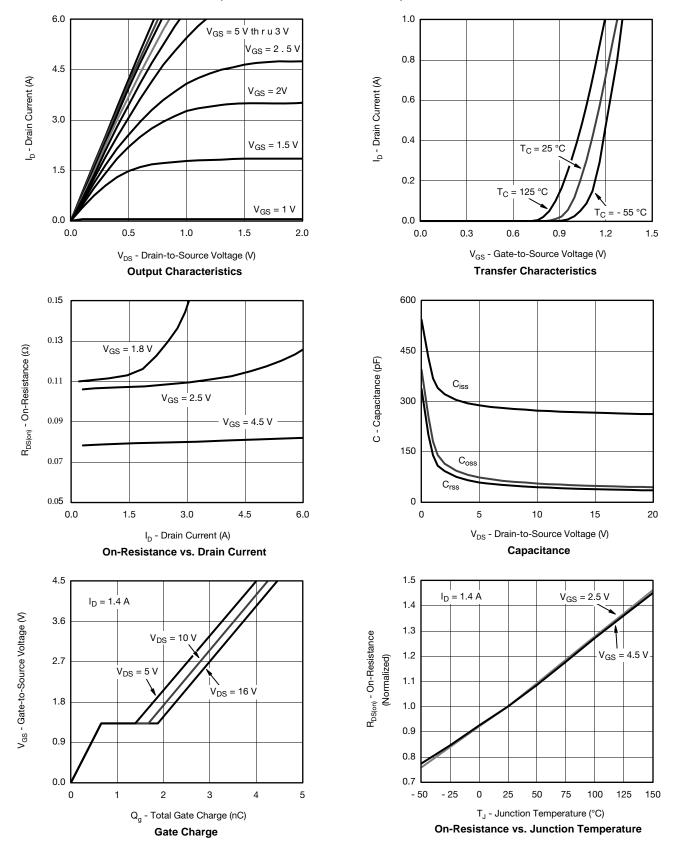
| Parameter                                     | Symbol                  | Test Conditions  | Min.   | Тур.  | Max.  | Unit   |
|---|-------------------------|--|--------|-------|-------|--------|
| Static  |                         |  |        | I.    | I.    |        |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>         | V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA   |        |       |       | V      |
| V <sub>DS</sub> Temperature Coefficient       | $\Delta V_{DS}/T_{J}$   | 'pc/T.   |        | - 14  |       | m\//°C |
| V <sub>GS(th)</sub> Temperature Coefficient   | $\Delta V_{GS(th)}/T_J$ | I <sub>D</sub> = - 250 μA  |        | 2.4   |       | mV/°C  |
| Gate-Source Threshold Voltage                 | V <sub>GS(th)</sub>     | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA                                | - 0.45 |       | - 1.5 | V      |
| Gate-Source Leakage                           | I <sub>GSS</sub>        | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$   |        |       | ± 100 | nA     |
| Zoro Coto Voltago Proin Current               |                         | V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V  |        |       | - 1   |        |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>        | V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C                      |        |       | - 10  | μA     |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>      | $V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$   | - 2    |       |       | Α      |
|   |                         | V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.4 A  |        | 0.080 |       | Ω      |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>     | V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1.2 A  |        | 0.120 |       |        |
|   | ` ,                     | V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.3 A  |        | 0.140 |       |        |
| Forward Transconductance <sup>a</sup>         | g <sub>fs</sub>         | V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 1.4 A  |        | 5     |       | S      |
| Dynamic <sup>b</sup>                          |                         |  |        |       |       |        |
| Input Capacitance                             | C <sub>iss</sub>        |  |        | 272   |       | pF     |
| Output Capacitance                            | C <sub>oss</sub>        | $V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$                            |        | 55    |       |        |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>        |  |        | 44    |       |        |
| T. 10 . 0                                     | Q <sub>g</sub>          | $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.4 \text{ A}$                    |        | 4.3   | 6.5   | nC     |
| Total Gate Charge                             |                         |  |        | 2.7   | 4.1   |        |
| Gate-Source Charge                            |                         | $V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -1.4 \text{ A}$                    |        | 0.7   |       |        |
| Gate-Drain Charge                             | $Q_{gd}$                |  |        | 1.0   |       |        |
| Gate Resistance                               | R <sub>q</sub>          | f = 1 MHz  | 1.4    | 7     | 14    | Ω      |
| Turn-On Delay Time                            | t <sub>d(on)</sub>      |  |        | 12    | 20    |        |
| Rise Time                                     | t <sub>r</sub>          | $V_{DD} = -10 \text{ V, R}_{L} = 9.1 \Omega$   |        | 20    | 30    | ns     |
| Turn-Off DelayTime                            | t <sub>d(off)</sub>     | $I_{D} \cong -1.1 \text{ A, V}_{GEN} = -4.5 \text{ V, R}_{g} = 1 \Omega$                     |        | 23    | 35    |        |
| Fall Time                                     | t <sub>f</sub>          |  |        | 9     | 18    |        |
| Turn-On Delay Time                            | t <sub>d(on)</sub>      |  |        | 5     | 10    |        |
| Rise Time                                     | t <sub>r</sub>          | $V_{DD} = -10 \text{ V}, R_1 = 9.1 \Omega$   |        | 10    | 20    |        |
| Turn-Off DelayTime                            | t <sub>d(off)</sub>     | $I_D \cong -1.1 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$                           |        | 18    | 27    |        |
| Fall Time                                     | t <sub>f</sub>          |  |        | 7     | 14    |        |
| Drain-Source Body Diode Characterist          |                         |  |        |       |       |        |
| Continuous Source-Drain Diode Current         | I <sub>S</sub>          | T <sub>C</sub> = 25 °C   |        |       | - 2.4 | А      |
| Pulse Diode Forward Current <sup>a</sup>      | I <sub>SM</sub>         | Ü  |        |       | - 6   |        |
| Body Diode Voltage                            | V <sub>SD</sub>         | I <sub>F</sub> = - 0.7 A   |        | - 0.8 | - 1.2 | V      |
| Body Diode Reverse Recovery Time              | t <sub>rr</sub>         | ·  |        | 18    | 27    | ns     |
| Body Diode Reverse Recovery Charge            | Q <sub>rr</sub>         |  |        | 7     | 14    | nC     |
| Reverse Recovery Fall Time                    | t <sub>a</sub>          | $I_F = -0.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ |        | 7     |       | ns     |
| Reverse Recovery Rise Time                    | t <sub>b</sub>          | 1  |        | 11    |       |        |

#### Notes:

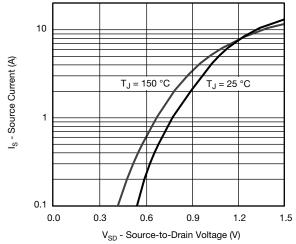
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

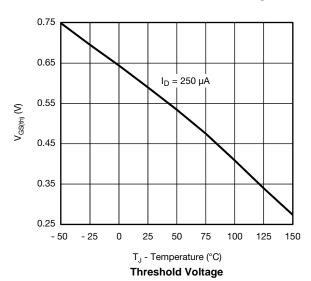


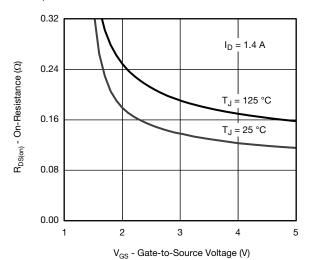




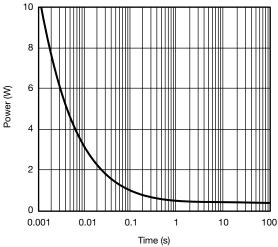


#### Source-Drain Diode Forward Voltage

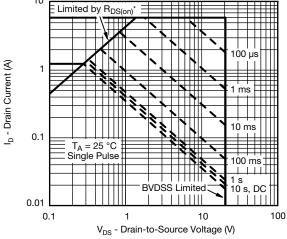




On-Resistance vs. Gate-to-Source Voltage



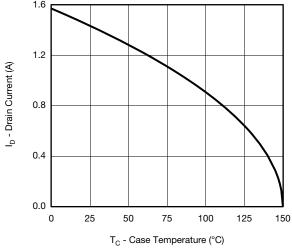
Single Pulse Power, Junction-to-Ambient



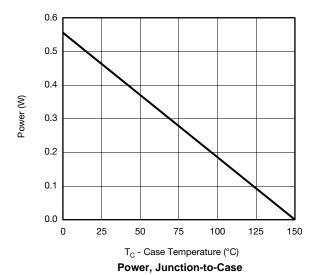
 $^{\star}\,V_{GS}\,{>}\,$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

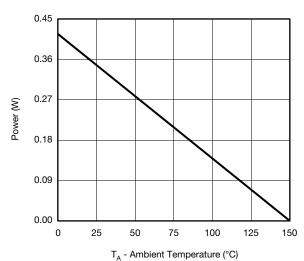
Safe Operating Area, Junction-to-Ambient





**Current Derating\*** 

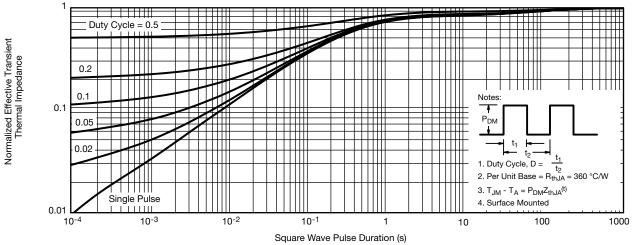




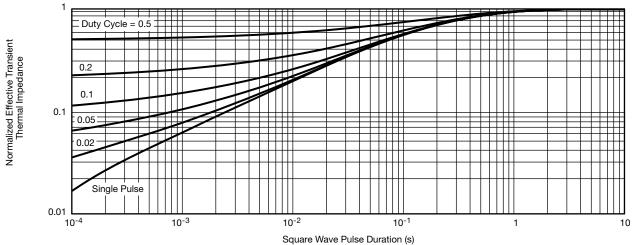
Power, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient



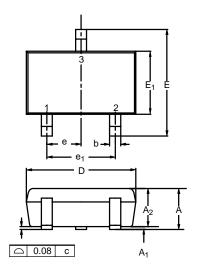
Normalized Thermal Transient Impedance, Junction-to-Foot

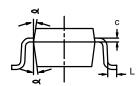
E-mail: China@VBsemi TEL:86-755-83251052

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## SC-70: 3-LEADS

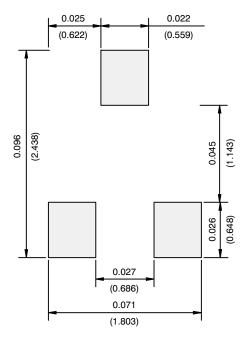




|                       | MIL     | LIMET          | ERS  | INCHES   |       |       |  |
|-----------------------|---------|----------------|------|----------|-------|-------|--|
| Dim                   | Min     | Nom            | Max  | Min      | Nom   | Max   |  |
| Α                     | 0.90    | -              | 1.10 | 0.035    | _     | 0.043 |  |
| A <sub>1</sub>        | -       | -              | 0.10 | -        | -     | 0.004 |  |
| A <sub>2</sub>        | 0.80    | -              | 1.00 | 0.031    | _     | 0.039 |  |
| b                     | 0.25    | -              | 0.40 | 0.010    | -     | 0.016 |  |
| С                     | 0.10    | -              | 0.25 | 0.004    | _     | 0.010 |  |
| D                     | 1.80    | 2.00           | 2.20 | 0.071    | 0.079 | 0.087 |  |
| Ε                     | 1.80    | 2.10           | 2.40 | 0.071    | 0.083 | 0.094 |  |
| E <sub>1</sub>        | 1.15    | 1.25           | 1.35 | 0.045    | 0.049 | 0.053 |  |
| е                     | 0.65BSC |                |      | 0.026BSC |       |       |  |
| <b>e</b> <sub>1</sub> | 1.20    | 1.30           | 1.40 | 0.047    | 0.051 | 0.055 |  |
| L                     | 0.10    | 0.20           | 0.30 | 0.004    | 0.008 | 0.012 |  |
| ٦                     | 7°Nom   |                |      | 7°Nom    |       |       |  |
| ECN: S-0<br>DWG: 5    |         | v. C, 09-Jul-0 | )1   | 1        |       |       |  |



### **RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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